

Title (en)  
Solder joint

Title (de)  
Lötverbindung

Title (fr)  
Liaison par brasage

Publication  
**EP 2437352 B1 20170308 (DE)**

Application  
**EP 11450127 A 20110929**

Priority  
AT 16382010 A 20100930

Abstract (en)  
[origin: EP2437352A1] The joint has a truncated cone or truncated pyramid recess (4) i.e. tapped blind hole, arranged in an upper surface (3) of an electrically conductive body (1). An electrically conductive pin (2) is partially arranged in the recess, and a solder material (7) is arranged in an intermediate space (5) between a lateral surface (6) of the recess and pin and partially arranged on the pin and lateral surface of the recess. A rounded or pointed end of the pin is arranged in the recess. A receiving opening i.e. through hole, is arranged adjacent to a bottom portion (8) of the recess. An independent claim is also included for a fuse base comprising contact pins.

IPC 8 full level  
**H01R 4/02** (2006.01); **F42B 3/103** (2006.01); **H01R 33/06** (2006.01)

CPC (source: EP)  
**F42B 3/103** (2013.01); **H01R 4/027** (2013.01); **H01R 33/06** (2013.01); **H01R 24/70** (2013.01)

Cited by  
AT513904A1; AT513904B1; AT513921A1; AT513921B1; WO2014115026A3

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)  
**EP 2437352 A1 20120404; EP 2437352 B1 20170308**; AT 510474 A1 20120415; AT 510474 B1 20131115

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